# UNITY OPTO TECHNOLOGY CO., LTD RELIABILITY TESTS

P/N:

**MSL-299SW** 

# **TEST ITEM:**

- **◆**OPERATION LIFE TEST
- **◆THERMAL SHOCK**
- **◆**TEMPERATURE CYCLE
- **◆**SOLDERABILITY
- **◆**SOLDER RESISTANCE
- **◆**HIGH TEMPERATURE STORAGE
- **◆LOW TEMPERATURE STORAGE**
- **◆LEVEL 2A TEST CONDITION**

## **OPERATION LIFT TEST**

DOC. NO.:QR460-1 Date: 12/20/2005

## 1.PURPOSE:

To test the Power Output and confirm the maximum Power Decay is lower than 20% after burn-in at room temperature ( $T_a = 25^{\circ}\mathbb{C}$ ).

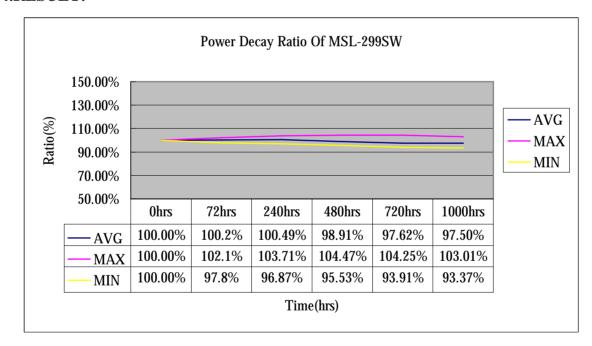
## 2.P/N:

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#### 3.TEST CONDITION:

- 1.  $T_a = 25 \pm 5$ °C
- 2.  $I_F = 20 \text{ mA}$
- 3. Time = 1000 hrs

#### 4.RESULT:



### **5.CONCLUSION:**

After 1000 hrs burn-in at Ta =  $25^{\circ}$ C, The max power decay is lower than 20%. The judgement is ACCEPT.

PREPARED BY:	Zhiyong Tsai	APPROVED BY:	J.M
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## THERMAL SHOCK

DOC. NO.:QR460-2 Date: 12/20/2005

## 1.PURPOSE:

To test for OPEN/SHORT after Air-to-Air Thermal Shock.

## 2.P/N:

MSL-299SW

### **3.TEST CONDITION:**

- 1. After IR Reflow
- 2.  $105\pm5^{\circ}$ C (10min)~-55 $\pm5^{\circ}$ C (10min) for 200 cycles.
- 3. Transfer time =  $5\pm 1$  min

## 4.RESULT:

- 1. Test item: OPEN/SHORT
- 2. Test result:

Sample Q'ty	Defec	Judgement		
Sample Q ty	OPEN	SHORT	Juagemen	
50	0	0	ACC	

## **5.CONCLUSION:**

After testing thermal shock for 200 cycles, all samples PASS. The judgement is ACCEPT.

PREPARED BY:	Zhiyong Tsai	APPROVED BY:	J.M
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## **TEMPERATURE CYCLE**

DOC. NO.:QR460-3 Date: 12/20/2005

#### 1.PURPOSE:

To test for OPEN/SHORT after Temperature Cycle.

## 2.P/N:

MSL-299SW

### 3.TEST CONDITION:

- 1. After IR Reflow
- 2.  $105\pm5^{\circ}$ C (30mins)~ $25^{\circ}$ C (5mins)~ $-55\pm5^{\circ}$ C (30mins)~ $25^{\circ}$ C (5mins) for 100 cycles.
- 3. Transfer time =  $5\pm 1$  min

## 4.RESULT:

- 1. Test item: OPEN/SHORT
- 2. Test result:

Sample Q'ty	Defec	Judgement		
Sample Q ty	OPEN	SHORT	Juagemen	
30	0	0	ACC	

## **5.CONCLUSION:**

After testing temperature cycle for 100 cycles, all samples PASS. The judgement is ACCEPT.

PREPARED BY:	Zhiyong Tsai	APPROVED BY:	J.M
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## **SOLDERABILITY**

DOC. NO.:QR460-4 Date: 12/20/2005

## 1.PURPOSE:

To visually test for solder coverage after soldering at 230 degrees C.

## 2.P/N:

MSL-299SW

## 3.TEST CONDITION:

- $1.T_{dipped area} = 230\pm 5 degrees C$
- $2.t_{dip} = 3sec$
- 3. Criteria: The solder coverage area should over 95%.

## 4.RESULT:

- 1. Test item: OPEN/SHORT
- 2. Test result:

Sample Q'ty	Defect Q'ty	Judgement
30	0	ACC

## **5.CONCLUSION:**

After soldering, all samples are PASS. The judgement is ACCEPT.

PREPARED BY:	Zhiyong Tsai	APPROVED BY:	J.M
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## **SOLDERABILITY RESISTANCE**

DOC. NO.:QR460-5 Date: 12/20/2005

## 1.PURPOSE:

To test for OPEN/SHORT after soldering at 260 $\pm$ 5°C.

## 2.P/N:

MSL-299SW

## 3.TEST CONDITION:

- 1.  $T_{\text{dipped area}} = 260 \pm 5^{\circ} \text{C}$
- 2.  $T_{dip} = 10 \pm 1 \text{sec}$

## 4.RESULT:

- 1. Test item: OPEN/SHORT
- 2. Test result:

Sample Q'ty	Defec	Judgement	
Sample Q ty	OPEN	SHORT	Juugemem
30	0	0	ACC

## **5.CONCLUSION:**

After soldering, all samples are PASS.

The judgement is ACCEPT

PREPARED BY:	Zhiyong Tsai	APPROVED BY:	J.M
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## **HIGH TEMPERATURE STORAGE**

DOC. NO.:QR460-6 Date: 12/20/2005

## 1.PURPOSE:

To test for OPEN/SHORT after High Temperature Storage.

## 2.P/N:

MSL-299SW

## 3.TEST CONDITION:

- 1.  $Ta = 105 \pm 5$ °C
- 2. Time = 1000 hrs

## 4.RESULT:

- 1. Test item: OPEN/SHORT
- 2. Test result:

Sample Q'ty	Defec	Indoomont	
Sample Q ty	OPEN	SHORT	Judgement
30	0	0	ACC

## **5.CONCLUSION:**

After testing high temperature storage for 1000hrs, all samples are PASS. The judgement is ACCEPT.

PREPARED BY:	Zhiyong Tsai	APPROVED BY:	J.M

## **LOW TEMPERATURE STORAGE**

DOC. NO.:QR460-7 Date: 12/20/2005

## 1.PURPOSE:

To test for OPEN/SHORT after Low Temperature Storage.

## 2.P/N:

MSL-299SW

## 3.TEST CONDITION:

- 1.  $T_a = -40 \pm 5^{\circ} C$
- 2. Time = 1000 hrs

## 4.RESULT:

- 1.Test item: OPEN/SHORT
- 2.Test result:

Sampla O'ty	Defect Q'ty		Indoomont	
Sample Q'ty	OPEN	SHORT	Judgemen	
30	0	0	ACC	

## **5.CONCLUSION:**

After testing low temperature storage for 1000hrs, all samples are PASS. The judgement is ACCEPT.

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## **LEVEL 2A TEST CONDITION**

DOC. NO.:QR460-8 Date: 12/20/2005

## 1.PURPOSE:

To test for OPEN/SHORT after Level 2A Test Condition.

## 2.P/N:

MSL-299SW

## **3.TEST CONDITION:**

- 1. Baking 20 hrs
- 2. 60°C / 60% RH 5 days
- 3. IR-Reflow 2 Times
- $4.105\pm5^{\circ}$ C (15min)~-55 $\pm5^{\circ}$ C (15min) for 100 cycles

## 4.RESULT:

- 1.Test item: OPEN/SHORT
- 2.Test result:

Sample Q'ty	Defect Q'ty		Indoomont
Sample Q ty	OPEN	SHORT	Judgement
50	0	0	ACC

## **5.CONCLUSION:**

After testing Level 2A for 100 cycles, all samples are PASS. The judgement is ACCEPT.

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